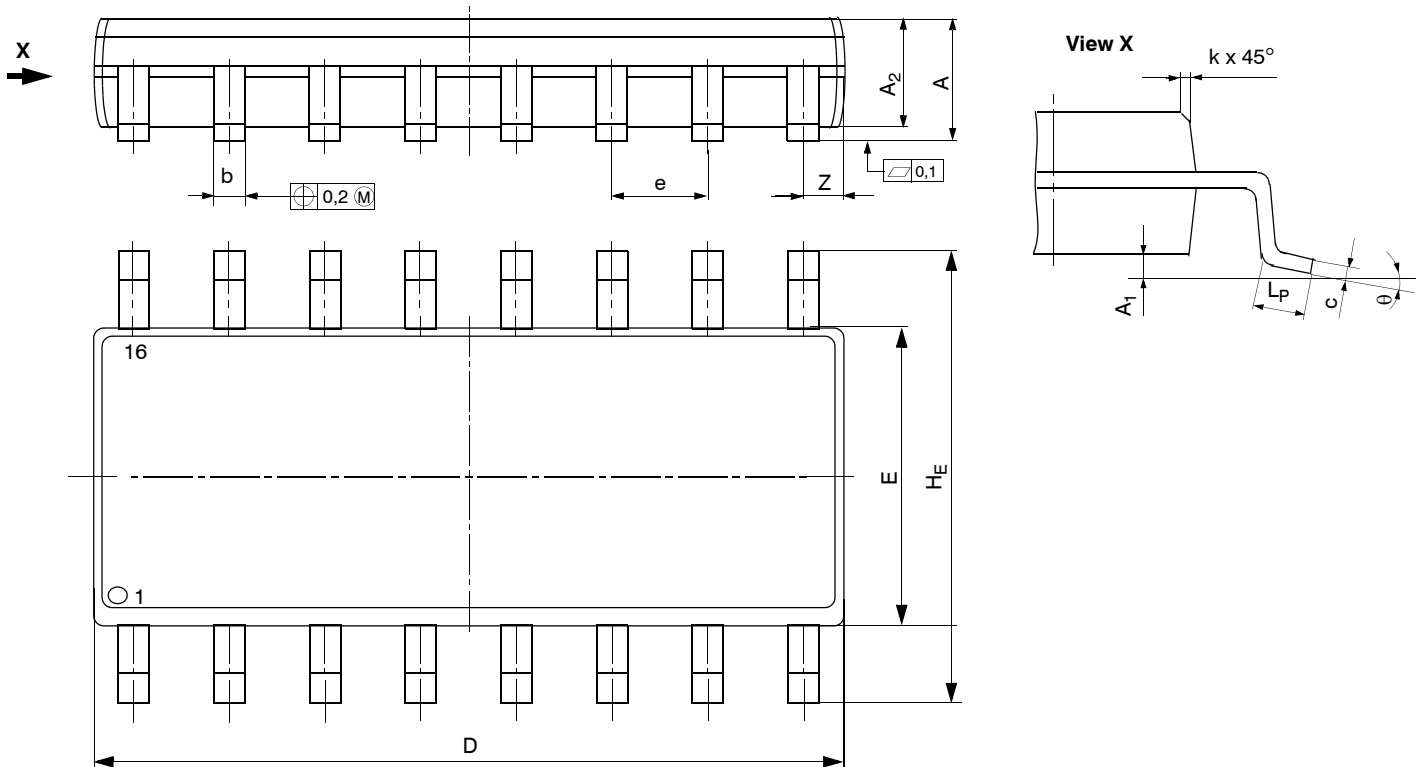
	<b>Package SOP16</b> (150 mil)	<b>MDS</b> <b>752</b>
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Dimensions in millimetres

Based on IEC 191-2Q: Type 076E07S

**1 Dimensions**

Dimensions of Sub-Group B1	
$A_{\max}$	1,73
$b_{P\min}$	0,35
$b_{P\max}$	0,49
$e_{\text{nom}}$	1,27
$H_{E\min}$	5,80
$H_{E\max}$	6,30
$L_{P\min}$	0,40
$Z_{\max}$	0,55

Dimensions of Sub-Group C1	
$A_{\min}$	1,55
$A_{1\min}$	0,127
$A_{1\max}$	0,25
$A_{2\min}$	1,40
$A_{2\max}$	1,55
$c_{\min}$	0,19
$c_{\max}$	0,25
$D_{\min}^*$	9,80
$D_{\max}^*$	9,98
$E_{\min}^*$	3,80
$E_{\max}^*$	4,00
$k_{\min}$	0,25
$\theta_{\min}$	0°
$\theta_{\max}$	8°

- 2 Weight**  $\leq 0,5$  g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** FeNi-Alloy or Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

\* without mold-flash

Zentrum Mikroelektronik Dresden AG		
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